

	Type	Hits	Search Text	DBs	Time Stamp
20	BRS	10	("4647477" "5465008" "5627406" "5653841" "6271579") .pn.	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/03/10 19:12
21	BRS	583	micro adj device and (housing package packaging)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/01 15:19
22	BRS	18	micro adj device and (housing package packaging) and palladium and tungsten	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/01 15:20
23	BRS	145	micro adj device and (housing package packaging) and (solder soldering soldered)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/01 15:16
24	BRS	15	micro adj device and (housing package packaging) and (solder soldering soldered) same palladium	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/01 15:16
25	BRS	6	micro adj device and (housing package packaging) and (solder soldering soldered) same tungsten	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/01 15:20
26	BRS	11	micro adj device and (housing package packaging) and palladium same tungsten	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/01 15:17
27	BRS	80	(MEMS micro adj device) and (housing package packaging) and (solder soldering soldered) and palladium same tungsten	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/01 15:21
28	BRS	10449	(MEMS micro adj device) and (housing package packaging)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/01 15:19

	Type	Hits	Search Text	DBs	Time Stamp
29	BRS	243	(MEMS micro adj device) and (housing package packaging) and palladium and tungsten	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/01 15:20
30	BRS	70	(MEMS micro adj device) and (housing package packaging) and (solder soldering soldered) same tungsten	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/14 15:45
31	BRS	8	(MEMS micro adj device) and (housing package packaging) and (solder soldering soldered) same palladium same tungsten	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/01 15:21
32	BRS	137	(MEMS micro adj device) and (housing package packaging) and palladium same tungsten	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/14 15:42
33	BRS	8	(MEMS micro adj device) and (housing package packaging) and (solder soldering soldered) same tungsten same (palladium)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/14 15:56
34	BRS	41	(MEMS micro adj device) and (housing package packaging) and (solder soldering soldered) same tungsten same (nickel copper)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/14 15:53
35	BRS	1370	257/704.ccls.	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:25
36	BRS	643	257/677.ccls.	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:24

	Type	Hits	Search Text	DBs	Time Stamp
37	BRS	25	(palladium Pd) with (tungsten W) same (solder soldering soldered) same (lid cover cap lead) and ceramic with (house housing package packaging packaged) same (device chip circuit cavity)	US -PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:45
38	BRS	2	"4833102".pn.	US -PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:56
39	BRS	39	(palladium Pd) with (tungsten W) same (solder soldering soldered) same (lid cover cap lead) and ceramic with (house housing package packaging packaged)	US -PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:44
40	BRS	57	(palladium Pd) with (tungsten W) same (solder soldering soldered) same (lid cover cap lead) and ceramic same (house housing package packaging packaged) same (device chip circuit cavity)	US -PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:44
41	BRS	77	(palladium Pd) with (tungsten W) same (solder soldering soldered) and ceramic with (house housing package packaging packaged)	US -PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:44
42	BRS	12	S42 and S55	US -PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:42
43	BRS	2	S39 and S55	US -PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:40

	Type	Hits	Search Text	DBs	Time Stamp
44	BRS	1	S38 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:40
45	BRS	0	S43 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:40
46	BRS	1	S40 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:40
47	BRS	0	S41 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:40
48	BRS	223	(palladium Pd) same (tungsten W) same (solder soldering soldered) and ceramic same (house housing package packaging packaged)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:43
49	BRS	26	S42 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:35
50	BRS	8	S43 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:34
51	BRS	0	S37 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:39

	Type	Hits	Search Text	DBs	Time Stamp
52	BRS	1	S41 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:34
53	BRS	1	S40 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:34
54	BRS	4	S39 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:32
55	BRS	2	S38 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:29
56	BRS	1	S37 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:39
57	BRS	824	(palladium Pd) same (tungsten W) same (solder soldering soldered)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:38
58	BRS	37912	(palladium Pd) same (tungsten W)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:27
59	BRS	1167	257/783.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:25
60	BRS	1182	257/779.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:25

	Type	Hits	Search Text	DBs	Time Stamp
61	BRS	1005	257/659.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:25
62	BRS	426	257/729.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:25
63	BRS	499	257/710.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/09/25 11:25